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Features:

- ♦ Fewer LEDs required.
- ♦ Low profile.
- ♦ Lowers lighting system cost.
- ♦ Super flux output.
- ♦ Viewing angle=70°.
- ♦ The product itself will remain within RoHS compliant Version.

Descriptions:

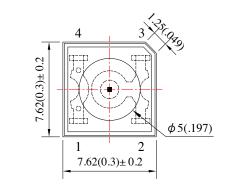
- ♦ This revolutionary package design allows the light designer to reduce the number of LEDs required and provide a more uniform and unique illuminated appearance than with other LED solutions.
- ♦ The low profile package can be easily coupled with reflectors or lenses to efficiently distribute light and provide the desired light appearance.

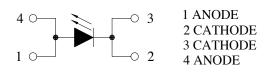
Applications:

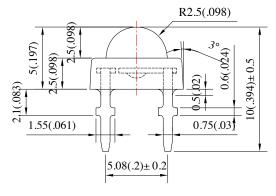
- Automotive exterior lighting.
- ♦ Electronic signs and signals.
- ♦ Special lighting application.

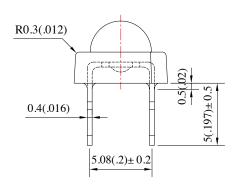
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Package Dimension:









Part No.	Chip Material	Lens Color	Source Color
U48B3C-B4-1G	InGaN	Water Clear	Blue

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is \pm 0.25mm (.010") unless otherwise noted.
- 3. An epoxy meniscus may extend about 1.50mm (.059") down the leads.
- 4. Specifications are subject to change without notice.

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Absolute Maximum Ratings at Ta=25 $^\circ$ C

Parameters	Symbol	Max.	Unit
Power Dissipation	PD	190	mW
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	IFP	100	mA
Forward Current	IF	50	mA
Reverse Voltage	VR	5	V
Electrostatic Discharge (HBM)	ESD	400 V	
Operating Temperature Range	Topr	-40℃ to +85℃	
Storage Temperature Range	Tstg	-40℃ to +100℃	
Lead Soldering Temperature	Tsld	260°C for 5 Seconds	

Electrical Optical Characteristics at Ta=25℃

Parameters	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Luminous Intensity (Note 1) *	IV	270	450		mcd	IF=20mA
Viewing Angle (Note 2) *	2θ _{1/2}		70		Deg	IF=20mA
Peak Emission Wavelength	λр		468		nm	IF=20mA
Dominant Wavelength (Note 3)	λd		470		nm	IF=20mA
Spectrum Radiation Bandwidth	Δλ		25		nm	IF=20mA
Forward Voltage	VF	2.80	3.20	3.80	V	IF=20mA
Reverse Current	IR			10	μΑ	V _R =5V

Notes:

- 1. Luminous Intensity (Flux) is measured with a light sensor and filter combination that approximates the CIE eye-response curve.
 - 2. $\theta_{1/2}$ is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. The dominant wavelength (λd) is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.

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Typical Electrical / Optical Characteristics Curves (25°C Ambient Temperature Unless Otherwise Noted) Forward Current & Forward Voltage Spectrum Distribution Ta=25°C 50 100 Relative Luminous Intensity (%) Forward Current IF (mA) 40 75 30 50 20 25 10 300 400 500 600 700 800 3.2 3.4 3.6 3.8 Forward Voltage VF (V) Wavelength $\lambda p (nm)$ Luminous Intensity & Luminous Intensity & Forward Current Ambient Temperature Ta=25°C Relative Luminous Intensity (%) 0001 01 01 11 f=1KHz 10 100 -60 -40 -20 0 20 40 60 80 100 10¹ 10^{2} Forward Current IF (mA) Ambient Temperature Ta (°C) Forward Current Derating Curve Radiation Diagram Ta=25°C 100 10° 20° Forward Current IF (mA) 30° 80 40° 60 50 1.0 50° 40 0.9 60° 0.8

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70° 80°

0.5 0.3 0.10 0.2 0.4 0.6

20

0

40

Ambient Temperature Ta (°C)

60

80

Reliability Test Items And Conditions:

The reliability of products shall be satisfied with items listed below:

Confidence level: 90%.

LTPD: 10%.

1) Test Items and Results:

Test Item	Standard Test Method	Test Conditions	Note	Number of Damaged
Resistance to Soldering Heat	JEITA ED-4701 300 302	Tsld=260±5℃, 10sec 3mm from the base of the epoxy bulb	1 time	0/100
Solder ability	JEITA ED-4701 300 303	Tsld=235 \pm 5 $^{\circ}$ C, 5sec (using flux)	1time over 95%	0/100
Thermal Shock	JEITA ED-4701 300 307	0℃~100℃ 15sec, 15sec	100 cycles	0/100
Temperature Cycle	JEITA ED-4701 100 105	-40℃~25℃~100℃~25℃ 30min,5min,30min,5min	100 cycles	0/100
Moisture Resistance Cycle	JEITA ED-4701 200 203	25℃~65℃~-10℃ 90%RH 24hrs/1cycle	10 cycles	0/100
High Temperature Storage	JEITA ED-4701 200 201	Ta=100℃	1000hrs	0/100
Terminal Strength (Pull test)	JEITA ED-4701 400 401	Load 10N (1kgf) 10±1sec	No noticeable damage	0/100
Terminal Strength (bending test)	JEITA ED-4701 400 401	Load 5N (0.5kgf) 0°~90°~0° bend 2 times	No noticeable damage	0/100
Temperature Humidity Storage	JEITA ED-4701 100 103	Ta=60℃, RH=90%	1000hrs	0/100
Low Temperature Storage	JEITA ED-4701 200 202	Ta=-40°C	1000hrs	0/100
Steady State Operating Life		Ta=25℃, IF=30mA	1000hrs	0/100
Steady State Operating Life of High Humidity Heat		Ta=60℃, RH=90%, IF=30mA	500hrs	0/100
Steady State Operating Life of Low Temperature		Ta=-30℃, IF=20mA	1000hrs	0/100

2) Criteria for Judging the Damage:

Item	Symbol	Test Conditions	Criteria for Judgment		
		rest Conditions	Min	Max	
Forward Voltage	VF	IF=20mA		F.V.*)×1.1	
Reverse Current	IR	VR=5V		F.V.*)×2.0	
Luminous Intensity	IV	IF=20mA	F.V.*)×0.7		

*) F.V.: First Value.

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Please read the following notes before using the product:

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 30° C or less and 80° RH or less.
- 2.3 The LEDs should be used within a year.
- 2.4 After opening the package, the LEDs should be kept at 30° C or less and 60° RH or less.
- 2.5 The LEDs should be used within 168 hours (7 days) after opening the package.

3. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 260° C for 5 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

4. Soldering

When soldering, for Lamp without stopper type and must be leave a minimum of 3mm clearance from the base of the lens to the soldering point.

To avoided the Epoxy climb up on lead frame and was impact to non-soldering problem, dipping the lens into the solder must be avoided.

Do not apply any external stress to the lead frame during soldering while the LED is at high temperature.

Recommended soldering conditions:

Soldering Iron		Wave Soldering		
Temperature Soldering Time	300℃ Max. 3 sec. Max. (one time only)	Pre-heat Pre-heat Time Solder Wave Soldering Time	100°C Max. 60 sec. Max. 260°C Max. 5 sec. Max.	

Note: Excessive soldering temperature and / or time might result in deformation of the LED lens or catastrophic failure of the LED.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

6. Caution in ESD

Static Electricity and surge damages the LED. It is recommended to use a wrist band or anti-electrostatic glove when handling the LED. All devices equipment and machinery must be properly grounded.

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